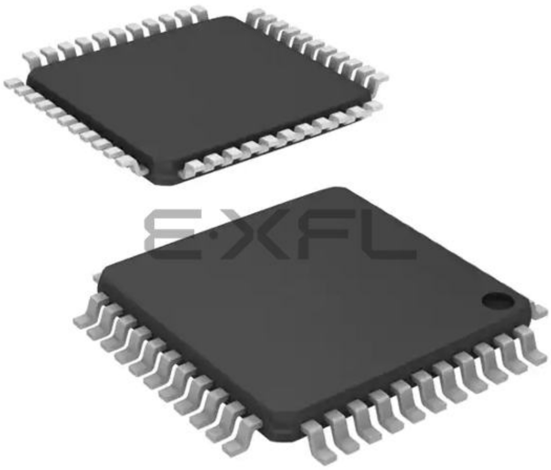

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	38
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 22x10b/12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08km204-i-pt

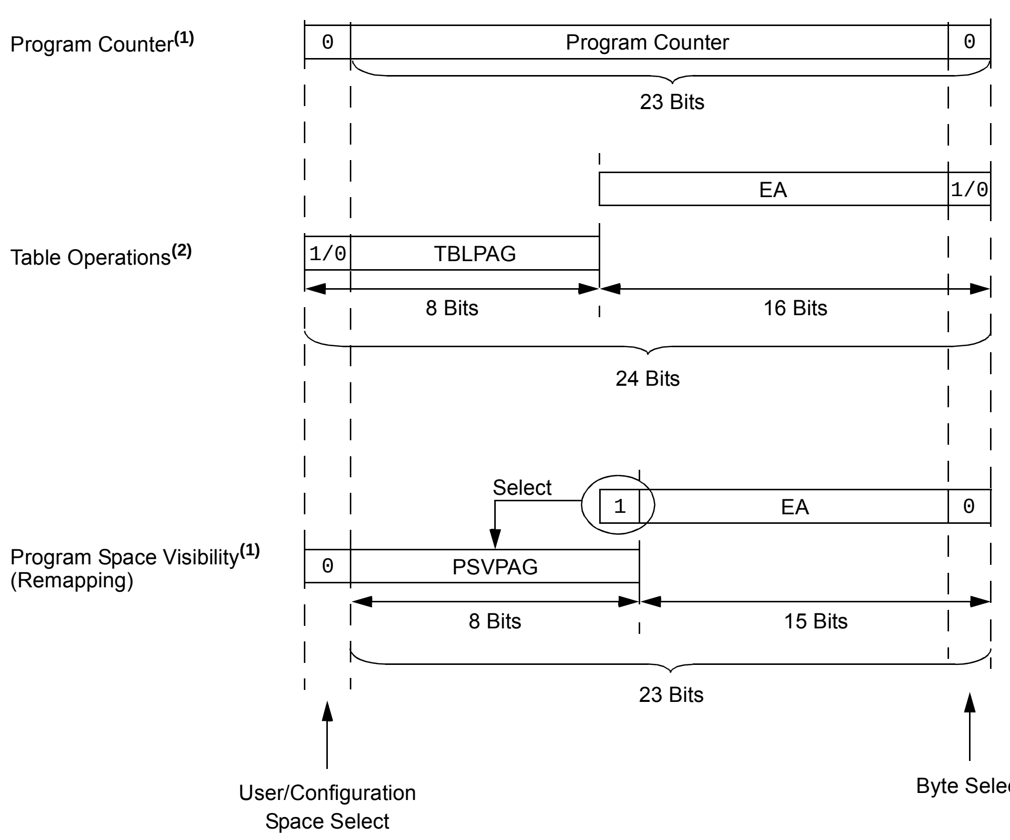
TABLE 4-35: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		
Program Space Visibility (Block Remap/Read)	User	0	PSVPAG<7:0>(2)		Data EA<14:0>(1)	
		0	xxxx xxxx		xxx xxxx xxxx xxxx	

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.

2: PSVPAG can have only two values ('00' to access program memory and FF to access data EEPROM) on the PIC24F16KM family.

FIGURE 4-5: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The LSb of program space addresses is always fixed as '0' in order to maintain word alignment of data in the program and Data Spaces.

2: Table operations are not required to be word-aligned. Table Read operations are permitted in the configuration memory space.

EXAMPLE 5-5: INITIATING A PROGRAMMING SEQUENCE – ASSEMBLY LANGUAGE CODE

```
        DISI    #5                          ; Block all interrupts
                                              for next 5 instructions
        MOV     #0x55, W0
        MOV     W0, NVMKEY                  ; Write the 55 key
        MOV     #0xAA, W1                   ;
        MOV     W1, NVMKEY                  ; Write the AA key
        BSET    NVMCON, #WR                 ; Start the erase sequence
        NOP                                 ; 2 NOPs required after setting WR
        NOP                                 ;
        BTSC    NVMCON, #15                 ; Wait for the sequence to be completed
        BRA     $-2                         ;
```

EXAMPLE 5-6: INITIATING A PROGRAMMING SEQUENCE – 'C' LANGUAGE CODE

```
// C example using MPLAB C30

asm("DISI #5");              // Block all interrupts for next 5 instructions

__builtin_write_NVM();       // Perform unlock sequence and set WR
```


6.0 DATA EEPROM MEMORY

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on data EEPROM, refer to the *"PIC24F Family Reference Manual"*, **"Data EEPROM"** (DS39720).

The data EEPROM memory is a Nonvolatile Memory (NVM), separate from the program and volatile data RAM. Data EEPROM memory is based on the same Flash technology as program memory, and is optimized for both long retention and a higher number of erase/write cycles.

The data EEPROM is mapped to the top of the user program memory space, with the top address at program memory address, 7FFE00h to 7FFFFFh. The size of the data EEPROM is 256 words in PIC24FXXXXX devices.

The data EEPROM is organized as 16-bit-wide memory. Each word is directly addressable, and is readable and writable during normal operation over the entire V_{DD} range.

Unlike the Flash program memory, normal program execution is not stopped during a data EEPROM program or erase operation.

The data EEPROM programming operations are controlled using the three NVM Control registers:

- NVMCON: Nonvolatile Memory Control Register
- NVMKEY: Nonvolatile Memory Key Register
- NVMADR: Nonvolatile Memory Address Register

6.1 NVMCON Register

The NVMCON register (Register 6-1) is also the primary control register for data EEPROM program/erase operations. The upper byte contains the control bits used to start the program or erase cycle and the flag bit to indicate if the operation was successfully performed. The lower byte of NVMCOM configures the type of NVM operation that will be performed.

6.2 NVMKEY Register

The NVMKEY is a write-only register that is used to prevent accidental writes or erasures of data EEPROM locations.

To start any programming or erase sequence, the following instructions must be executed first, in the exact order provided:

1. Write 55h to NVMKEY.
2. Write AAh to NVMKEY.

After this sequence, a write will be allowed to the NVMCON register for one instruction cycle. In most cases, the user will simply need to set the WR bit in the NVMCON register to start the program or erase cycle. Interrupts should be disabled during the unlock sequence.

The MPLAB® C30 C compiler provides a defined library procedure (`builtin_write_NVM`) to perform the unlock sequence. Example 6-1 illustrates how the unlock sequence can be performed with in-line assembly.

EXAMPLE 6-1: DATA EEPROM UNLOCK SEQUENCE

```
//Disable Interrupts For 5 instructions
asm volatile   ("disi #5");
//Issue Unlock Sequence
asm volatile   ("mov #0x55, W0    \n"
               "mov W0, NVMKEY    \n"
               "mov #0xAA, W1     \n"
               "mov W1, NVMKEY    \n");
// Perform Write/Erase operations
asm volatile   ("bset NVMCON, #WR  \n"
               "nop               \n"
               "nop               \n");
```

REGISTER 7-1: RCON: RESET CONTROL REGISTER(1)

R/W-0, HS	R/W-0, HS	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	SBOREN	RETEN(3)	—	—	CM	PMSLP
bit 15							bit 8

R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-0, HS	R/W-1, HS	R/W-1, HS
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or Uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or Uninitialized W Reset has not occurred

bit 13 **SBOREN:** Software Enable/Disable of BOR bit
1 = BOR is turned on in software
0 = BOR is turned off in software

bit 12 **RETEN:** Retention Sleep Mode(3)
1 = Regulated voltage supply provided by the Retention Regulator (RETREG) during Sleep
0 = Regulated voltage supply provided by the main Voltage Regulator (VREG) during Sleep

bit 11-10 **Unimplemented:** Read as ‘0’

bit 9 **CM:** Configuration Word Mismatch Reset Flag bit
1 = A Configuration Word Mismatch Reset has occurred
0 = A Configuration Word Mismatch Reset has not occurred

bit 8 **PMSLP:** Program Memory Power During Sleep bit
1 = Program memory bias voltage remains powered during Sleep
0 = Program memory bias voltage is powered down during Sleep and the voltage regulator enters Standby mode

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software RESET (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.
2: If the FWDTEN<1:0> Configuration bits are ‘11’ (unprogrammed), the WDT is always enabled regardless of the SWDTEN bit setting.
3: This is implemented on PIC24FV16KMXXX parts only; not used on PIC24F16KMXXX devices.

REGISTER 8-10: IFS5: INTERRUPT FLAG STATUS REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	—	—	—	—	—	ULPWUIF
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as ‘0’

bit 0 **ULPWUIF:** Ultra Low-Power Wake-up Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 8-11: IFS6: INTERRUPT FLAG STATUS REGISTER 6

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS	R/W-0, HS
—	—	—	—	—	—	CLC2IF	CLC1IF
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-2 **Unimplemented:** Read as ‘0’

bit 1 **CLC2IF:** Configurable Logic Cell 2 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **CLC1IF:** Configurable Logic Cell 1 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 8-31: IPC18: INTERRUPT PRIORITY CONTROL REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	HLVDIP2	HLVDIP1	HLVDIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as ‘0’

bit 2-0 **HLVDIP<2:0>:** High/Low-Voltage Detect Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-35: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

R-0	U-0	R/W-0	U-0	R-0	R-0	R-0	R-0
CPUIRQ	—	VHOLD	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
—	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CPUIRQ:** Interrupt Request from Interrupt Controller CPU bit

1 = An interrupt request has occurred but has not yet been Acknowledged by the CPU (this will happen when the CPU priority is higher than the interrupt priority)

0 = No interrupt request is left unacknowledged

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **VHOLD:** Vector Hold bit

Allows Vector Number Capture and Changes which Interrupt is Stored in the VECNUM<6:0> bits:

1 = VECNUM<6:0> will contain the value of the highest priority pending interrupt, instead of the current interrupt

0 = VECNUM<6:0> will contain the value of the last Acknowledged interrupt (last interrupt that has occurred with higher priority than the CPU, even if other interrupts are pending)

bit 12 **Unimplemented:** Read as ‘0’

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits

1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **VECNUM<6:0>:** Vector Number of Pending Interrupt bits

0111111 = Interrupt vector pending is Number 135
•
•
•
0000001 = Interrupt vector pending is Number 9
0000000 = Interrupt vector pending is Number 8

The following code sequence for a clock switch is recommended:

1. Disable interrupts during the OSCCON register unlock and write sequence.
2. Execute the unlock sequence for the OSCCON high byte by writing 78h and 9Ah to OSCCON<15:8>, in two back-to-back instructions.
3. Write the new oscillator source to the NOSCx bits in the instruction immediately following the unlock sequence.
4. Execute the unlock sequence for the OSCCON low byte by writing 46h and 57h to OSCCON<7:0>, in two back-to-back instructions.
5. Set the OSWEN bit in the instruction immediately following the unlock sequence.
6. Continue to execute code that is not clock-sensitive (optional).
7. Invoke an appropriate amount of software delay (cycle counting) to allow the selected oscillator and/or PLL to start and stabilize.
8. Check to see if OSWEN is '0'. If it is, the switch was successful. If OSWEN is still set, then check the LOCK bit to determine the cause of failure.

The core sequence for unlocking the OSCCON register and initiating a clock switch is shown in Example 9-1 and Example 9-2.

EXAMPLE 9-1: ASSEMBLY CODE SEQUENCE FOR CLOCK SWITCHING

```
;Place the new oscillator selection in W0
;OSCCONH (high byte) Unlock Sequence
MOV        #OSCCONH, w1
MOV        #0x78, w2
MOV        #0x9A, w3
MOV.b      w2, [w1]
MOV.b      w3, [w1]
;Set new oscillator selection
MOV.b      WREG, OSCCONH
;OSCCONL (low byte) unlock sequence
MOV        #OSCCONL, w1
MOV        #0x46, w2
MOV        #0x57, w3
MOV.b      w2, [w1]
MOV.b      w3, [w1]
;Start oscillator switch operation
BSET       OSCCON,#0
```

EXAMPLE 9-2: BASIC 'C' CODE SEQUENCE FOR CLOCK SWITCHING

```
//Use compiler built-in function to write
new clock setting
__builtin_write_OSCCONH(0x01); //0x01
switches to FRCPLL

//Use compiler built-in function to set the
OSWEN bit.
__builtin_write_OSCCONL(OSCCONL | 0x01);

//Optional: Wait for clock switch sequence
to complete
while(OSCCONbits.OSWEN == 1);
```

9.5 Reference Clock Output

In addition to the CLKO output (FOSC/2) available in certain oscillator modes, the device clock in the PIC24FXXXXX family devices can also be configured to provide a reference clock output signal to a port pin. This feature is available in all oscillator configurations and allows the user to select a greater range of clock submultiples to drive external devices in the application.

This reference clock output is controlled by the REFOCON register (Register 9-4). Setting the ROEN bit (REFOCON<15>) makes the clock signal available on the REFO pin. The RODIV<3:0> bits (REFOCON<11:8>) enable the selection of 16 different clock divider options.

The ROSSLP and ROSEL bits (REFOCON<13:12>) control the availability of the reference output during Sleep mode. The ROSEL bit determines if the oscillator on OSC1 and OSC2, or the current system clock source, is used for the reference clock output. The ROSSLP bit determines if the reference source is available on REFO when the device is in Sleep mode.

To use the reference clock output in Sleep mode, both the ROSSLP and ROSEL bits must be set. The device clock must also be configured for one of the primary modes (EC, HS or XT); otherwise, if the ROSEL bit is not also set, the oscillator on OSC1 and OSC2 will be powered down when the device enters Sleep mode. Clearing the ROSEL bit allows the reference output frequency to change as the system clock changes during any clock switches.

REGISTER 13-4: CCPxCON2H: CCPx CONTROL 2 HIGH REGISTERS

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
OENSYNC	—	OCFEN(1)	OCEEN(1)	OCDEN(1)	OCCEN(1)	OCBEN(1)	OCAEN
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ICGSM1	ICGSM0	—	AUXOUT1	AUXOUT0	ICS2	ICS1	ICS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **OENSYNC:** Output Enable Synchronization bit

1 = Update by output enable bits occurs on the next Time Base Reset or rollover
0 = Update by output enable bits occurs immediately

bit 14 **Unimplemented:** Read as ‘0’

bit 13-8 **OC<F:A>EN:** Output Enable/Steering Control bits(1)

1 = OCx pin is controlled by the CCPx module and produces an output compare or PWM signal
0 = OCx pin is not controlled by the CCPx module; the pin is available to the port logic or another peripheral multiplexed on the pin

bit 7-6 **ICGSM<1:0>:** Input Capture Gating Source Mode Control bits

11 = Reserved
10 = One-Shot mode: Falling edge from gating source disables future capture events (ICDIS = 1)
01 = One-Shot mode: Rising edge from gating source enables future capture events (ICDIS = 0)
00 = Level-Sensitive mode: A high level from gating source will enable future capture events; a low level will disable future capture events

bit 5 **Unimplemented:** Read as ‘0’

bit 4-3 **AUXOUT<1:0>:** Auxiliary Output Signal on Event Selection bits

11 = Input capture or output compare event; no signal in Timer mode
10 = Signal output is defined by module operating mode (see Table 13-5)
01 = Time base rollover event (all modes)
00 = Disabled

bit 2-0 **ICS<2:0>:** Input Capture Source Select bits

111 = Unused
110 = CLC2 output
101 = CLC1 output
100 = Unused
011 = Comparator 3 output
010 = Comparator 2 output
001 = Comparator 1 output
000 = Input Capture x (ICx) I/O pin

Note 1: OCFEN through OCBEN (bits<13:9>) are implemented in MCCPx modules only.

REGISTER 14-1: SSPxSTAT: MSSPx STATUS REGISTER (SPI MODE)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE(1)	D/$\overline{\text{A}}$	P	S	R/$\overline{\text{W}}$	UA	BF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7 **SMP:** Sample bit
SPI Master mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time
SPI Slave mode:
SMP must be cleared when SPI is used in Slave mode.

bit 6 **CKE:** SPI Clock Select bit(1)
1 = Transmit occurs on transition from active to Idle clock state
0 = Transmit occurs on transition from Idle to active clock state

bit 5 **D/$\overline{\text{A}}$:** Data/$\overline{\text{Address}}$ bit
Used in I^2C™ mode only.

bit 4 **P:** Stop bit
Used in I^2C mode only. This bit is cleared when the MSSPx module is disabled; SSPEN bit is cleared.

bit 3 **S:** Start bit
Used in I^2C mode only.

bit 2 **R/$\overline{\text{W}}$:** Read/$\overline{\text{Write}}$ Information bit
Used in I^2C mode only.

bit 1 **UA:** Update Address bit
Used in I^2C mode only.

bit 0 **BF:** Buffer Full Status bit
1 = Receive is complete, SSPxBUF is full
0 = Receive is not complete, SSPxBUF is empty

Note 1: Polarity of clock state is set by the CKP bit (SSPxCON1<4>).

16.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Real-Time Clock and Calendar, refer to the *"PIC24F Family Reference Manual"*, **"Real-Time Clock and Calendar (RTCC)"** (DS39696).

The RTCC provides the user with a Real-Time Clock and Calendar (RTCC) function that can be calibrated.

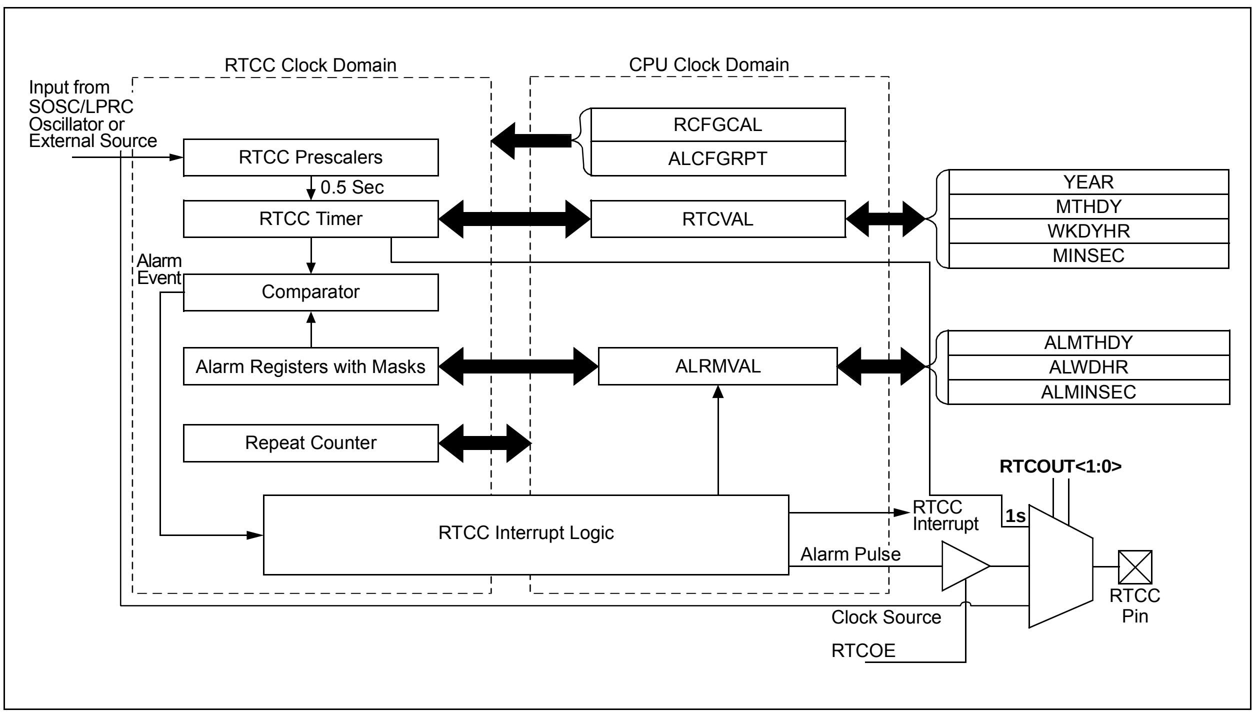
Key features of the RTCC module are:

- Operates in Sleep and Retention Sleep modes
- Selectable clock source
- Provides hours, minutes and seconds using 24-hour format
- Visibility of one half second period
- Provides calendar – weekday, date, month and year
- Alarm-configurable for half a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month or one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat chime
- Year 2000 to 2099 leap year correction
- BCD format for smaller software overhead
- Optimized for long term battery operation
- User calibration of the 32.768 kHz clock crystal/32K INTRC frequency with periodic auto-adjust
- Optimized for long term battery operation
- Fractional second synchronization
- Calibration to within ±2.64 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Ability to periodically wake-up external devices without CPU intervention (external power control)
- Power control output for external circuit control
- Calibration takes effect every 15 seconds
- Runs from any one of the following:
  - External Real-Time Clock of 32.768 kHz
  - Internal 31.25 kHz LPRC Clock
  - 50 Hz or 60 Hz External Input

16.1 RTCC Source Clock

The user can select between the SOSC crystal oscillator, LPRC internal oscillator or an external 50 Hz/60 Hz power line input as the clock reference for the RTCC module. This gives the user an option to trade off system cost, accuracy and power consumption, based on the overall system needs.

FIGURE 16-1: RTCC BLOCK DIAGRAM



REGISTER 19-8: AD1CSSH: A/D INPUT SCAN SELECT REGISTER (HIGH WORD)(1)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
—	CSS30	CSS29	CSS28	CSS27	CSS26	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS23	CSS22	CSS21	CSS20(2)	CSS19(2)	CSS18	CSS17	CSS16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-10 **CSS<30:26>:** A/D Input Scan Selection bits
1 = Includes the corresponding channel for input scan
0 = Skips the channel for input scan

bit 9-8 **Unimplemented:** Read as ‘0’

bit 7-0 **CSS<23:16>:** A/D Input Scan Selection bits(2)
1 = Includes the corresponding channel for input scan
0 = Skips the channel for input scan

Note 1: Unimplemented channels are read as ‘0’. Do not select unimplemented channels for sampling as indeterminate results may be produced.
2: The CSS<20:19> bits are not implemented in 20-pin devices.

REGISTER 19-9: AD1CSSL: A/D INPUT SCAN SELECT REGISTER (LOW WORD)(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS15	CSS14	CSS13	CSS12	CSS11	CSS10	CSS9	CSS8(2,3)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS7(2,3)	CSS6(2,3)	CSS5(2)	CSS4	CSS3	CSS2	CSS1	CSS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **CSS<15:0>:** A/D Input Scan Selection bits(2,3)
1 = Includes the corresponding ANx input for scan
0 = Skips the channel for input scan

Note 1: Unimplemented channels are read as ‘0’. Do not select unimplemented channels for sampling as indeterminate results may be produced.
2: The CSS<8:5> bits are not implemented in 20-pin devices.
3: The CSS<8:6> bits are not implemented in 28-pin devices.

19.2 A/D Sampling Requirements

The analog input model of the 12-bit A/D Converter is shown in Figure 19-2. The total sampling time for the A/D is a function of the holding capacitor charge time.

For the A/D Converter to meet its specified accuracy, the Charge Holding Capacitor (C_{HOLD}) must be allowed to fully charge to the voltage level on the analog input pin. The Source Impedance (R_S), the Interconnect Impedance (R_{IC}) and the Internal Sampling Switch Impedance (R_{SS}) combine to directly affect the time required to charge C_{HOLD}. The combined impedance of the analog sources must, therefore, be small enough to fully charge the holding capacitor within the chosen sample time. To minimize the effects of pin leakage currents on the accuracy of the A/D Converter, the maximum recommended source impedance, R_S, is 2.5 kΩ. After the analog input channel is selected (changed), this sampling function must be completed prior to starting the conversion. The internal holding capacitor will be in a discharged state prior to each sample operation.

At least 1 T_{AD} time period should be allowed between conversions for the sample time. For more details, see **Section 27.0 "Electrical Characteristics"**.

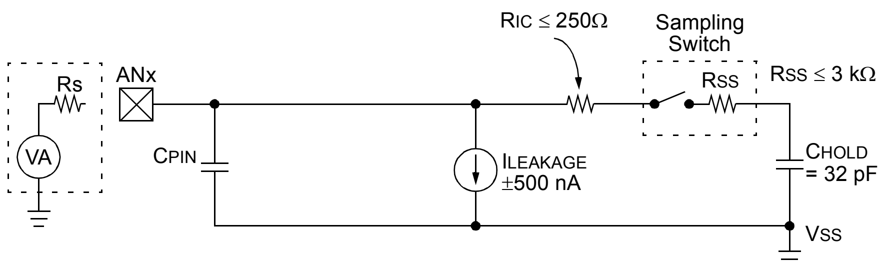
EQUATION 19-1: A/D CONVERSION CLOCK PERIOD

$$T_{AD} = T_{CY}(ADCS + 1)$$

$$ADCS = \frac{T_{AD}}{T_{CY}} - 1$$

Note: Based on $T_{CY} = 2/F_{OSC}$; Doze mode and PLL are disabled.

FIGURE 19-2: 12-BIT A/D CONVERTER ANALOG INPUT MODEL



Legend:
- C_{PIN} = Input Capacitance
- V_T = Threshold Voltage
- $I_{LEAKAGE}$ = Leakage Current at the Pin Due to Various Junctions
- R_{IC} = Interconnect Resistance
- R_{SS} = Sampling Switch Resistance
- C_{HOLD} = Sample-and-Hold Capacitance (from DAC)

Note: The C_{PIN} value depends on the device package and is not tested. The effect of C_{PIN} is negligible if $R_S \le 5$ kΩ.

TABLE 27-21: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Sym	Characteristic(1)	Min	Typ(2)	Max	Units	Conditions
OS50	FPLLI	PLL Input Frequency Range	4	—	8	MHz	ECPLL, HSPLL modes, -40°C ≤ TA ≤ +85°C
OS51	FSYS	PLL Output Frequency Range	16	—	32	MHz	-40°C ≤ TA ≤ +85°C
OS52	TLOCK	PLL Start-up Time (Lock Time)	—	1	2	ms	
OS53	DCLK	CLKO Stability (Jitter)	-2	1	2	%	Measured over 100 ms period

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 27-22: INTERNAL RC OSCILLATOR ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Characteristic	Min	Typ	Max	Units	Conditions	
F20	FRC @ 8 MHz(1)	-2	—	+2	%	+25°C	3.0V ≤ VDD ≤ 3.6V, F device 3.2V ≤ VDD ≤ 5.5V, FV device
		-5	—	+5	%	-40°C ≤ TA ≤ +125°C	1.8V ≤ VDD ≤ 3.6V, F device 2.0V ≤ VDD ≤ 5.5V, FV device
F21	LPRC @ 31 kHz(2)	-15	—	+15	%	-40°C ≤ TA ≤ +125°C	1.8V ≤ VDD ≤ 3.6V, F device 2.0V ≤ VDD ≤ 5.5V, FV device

Note 1: The frequency is calibrated at +25°C and 3.3V. The OSCTUN bits can be used to compensate for temperature drift.

2: The change of LPRC frequency as VDD changes.

TABLE 27-23: INTERNAL RC OSCILLATOR SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Sym	Characteristic	Min	Typ	Max	Units	Conditions
	TFRC	FRC Start-up Time	—	5	—	μs	
	TLPRC	LPRC Start-up Time	—	70	—	μs	

FIGURE 27-9: BROWN-OUT RESET CHARACTERISTICS

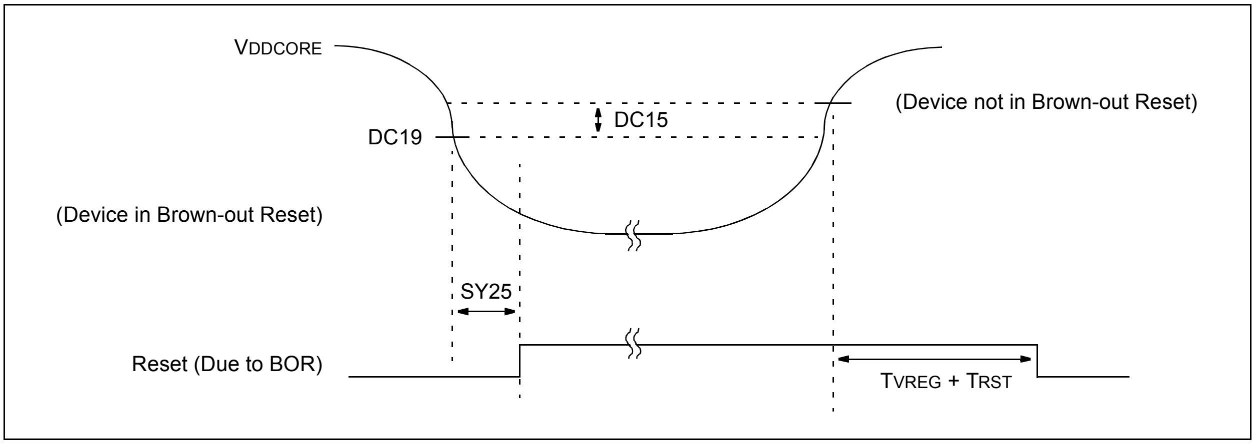


TABLE 27-25: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
SY10	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	
SY11	TPWRT	Power-up Timer Period	50	64	90	ms	
SY12	TPOR	Power-on Reset Delay	1	5	10	µs	
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	100	ns	
SY20	TWDT	Watchdog Timer Time-out Period	0.85	1.0	1.15	ms	1.32 prescaler
			3.4	4.0	4.6	ms	1:128 prescaler
SY25	TBOR	Brown-out Reset Pulse Width	1	—	—	µs	
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	2.0	2.3	µs	
SY45	TRST	Internal State Reset Time	—	5	—	µs	
SY50	TVREG	On-Chip Voltage Regulator Output Delay	—	10	—	µs	**(Note 2)**
SY55	TLOCK	PLL Start-up Time	—	100	—	µs	
SY65	TOST	Oscillator Start-up Time	—	1024	—	TOSC	
SY71	TPM	Program Memory Wake-up Time	—	1	—	µs	Sleep wake-up with PMSLP = 0
SY72	TLVR	Low-Voltage Regulator Wake-up Time	—	250	—	µs	

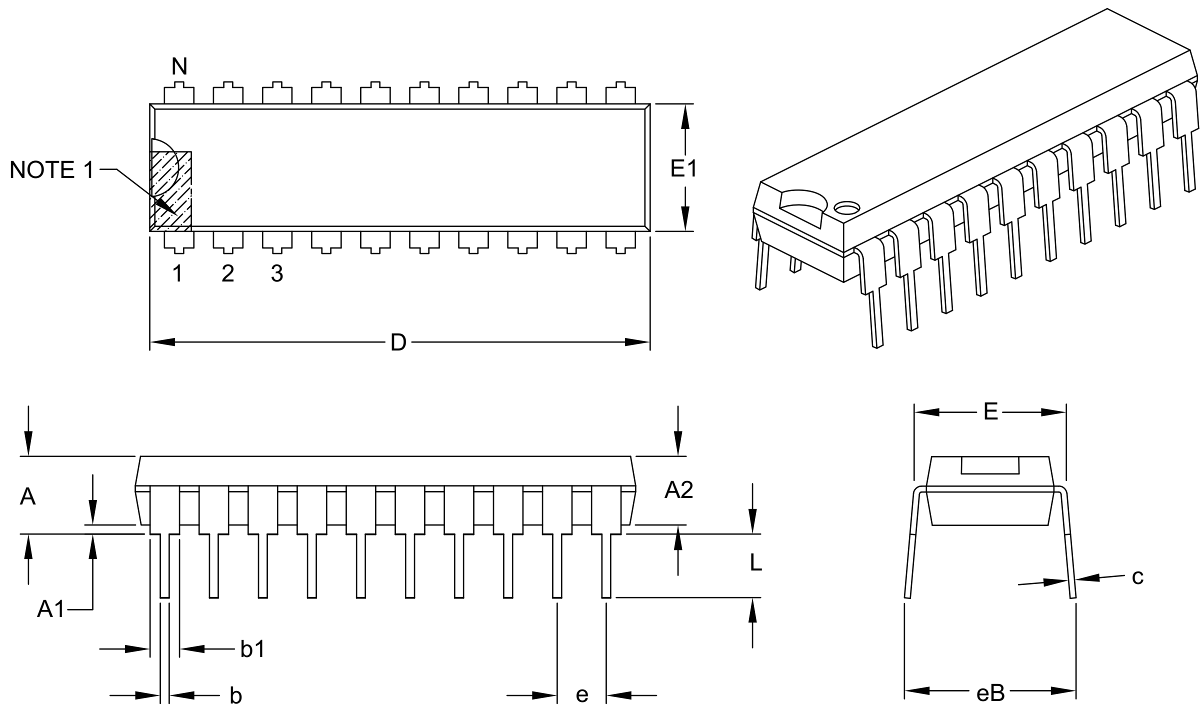
Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.
2: This applies to PIC24FV16KMXXX devices only.

28.2 Package Details

The following sections give the technical details of the packages.

20-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.980	1.030	1.060
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

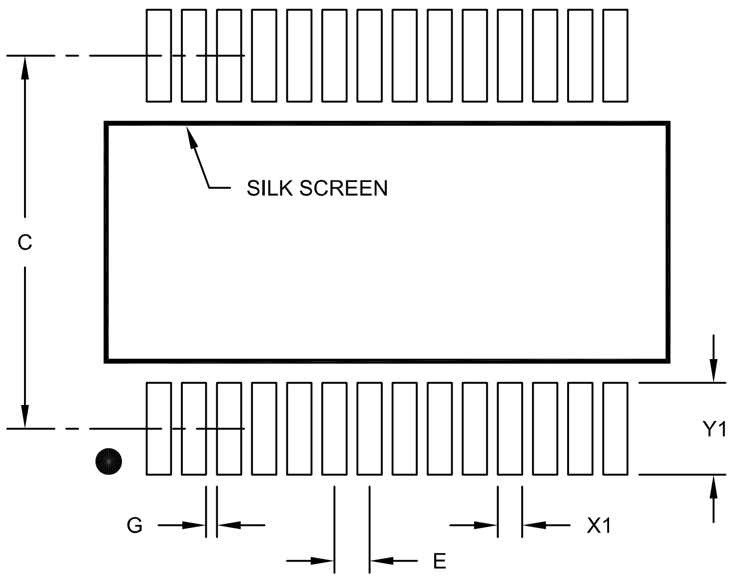
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-019B

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

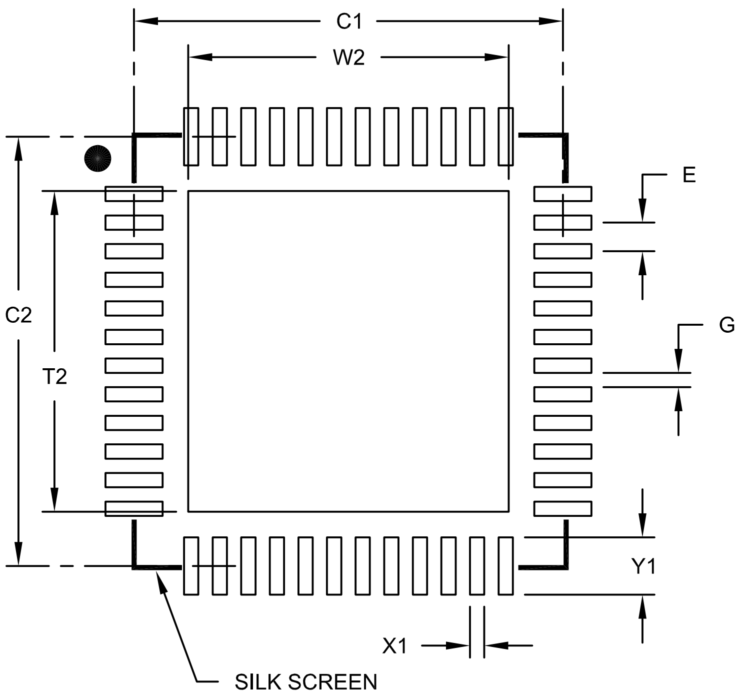
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN]
With 0.40 mm Contact Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A

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